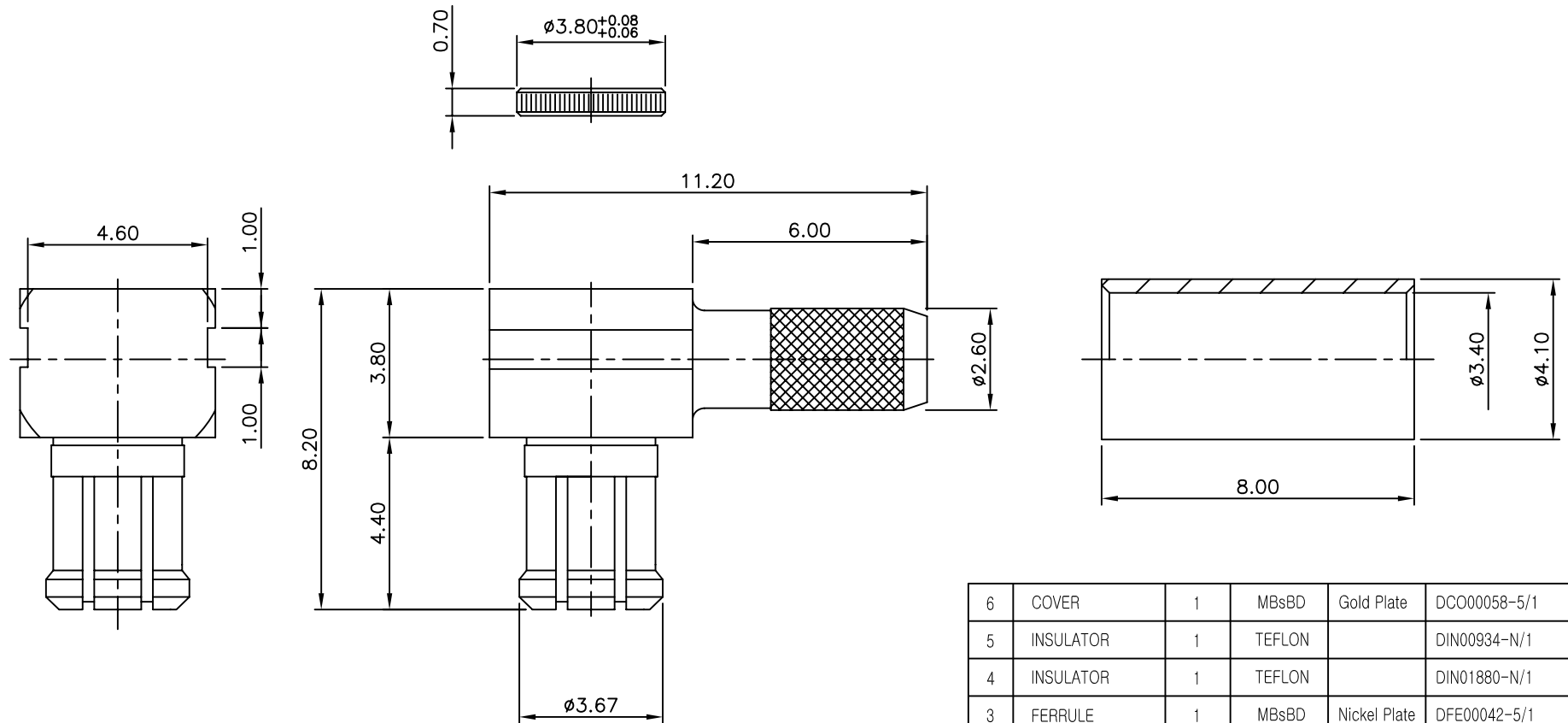


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1R	Initial Registration	S.M.LEE	I.C.KIM	2014.10.02.
1	[설번No.202002-0003] JACK 낙시바늘 추가	S.Y.EUN	I.C.KIM	2020.02.10.
2	커넥터 압착부 바디 부러짐 현상 방지로 인한 R추가	S.Y.EUN	I.C.KIM	2021.12.21.



1 2	6	COVER	1	MBsBD	Gold Plate	DCO00058-5/1	
	5	INSULATOR	1	TEFLON		DIN00934-N/1	
	4	INSULATOR	1	TEFLON		DIN01880-N/1	
	3	FERRULE	1	MBsBD	Nickel Plate	DFE00042-5/1	
	2	CONTACT	1	BeCu	Gold Plate	DCT01667-5/1	
	1	1-2 JACK	1	MBsBD	Gold Plate	DBB00284-3/2	DJA00008-5/1
1	1-1 BODY	1	MBsBD	Gold Plate	DBD00039-5/1		
	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE	

TOLERANCE	Decimal	DATE			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017		
	±0.1	2021. 12. 21.					
	Angle	APPROVED BY	I.C.KIM		KJ COMTECH CO.,LTD.		
±1°	CHECKED BY						
MATERIAL		DRAWN BY		S.Y.EUN		TITLE	
						MCX50 CABLE PL RG316DS	
FINISH		SCALE	UNIT		A4	DWG NO.	CN00714-7/4
						REVISION	2
		6/1		mm			